Product Specification

1~3m 400G OSFP Finned Top to 2× 200G QSFP56 Passive Direct Attach Copper Breakout Cable

PN:O400-2Q200-C



Features

- Supports 400G to 2×200G breakout
- 8 × 53.125 Gb/s PAM4 electrical lanes
- Four electrical lanes allocated to each 200G QSFP56 branch
- Wire gauge: 26 AWG, 28 AWG and 30 AWG
- Available in 0.5–3 m lengths
- Passive shielded twinax copper cable design
- Hot-pluggable OSFP and QSFP56 interfaces
- Low power dissipation of less than 0.1 W per end
- Two-wire I²C interface with customizable EEPROM identification
- Commercial operating temperature range: 0°C to +70°C

Compliance

- Compliant with OSFP MSA
- Compliant with QSFP56 MSA
- Compliant with SFF-8679 electrical interface requirements
- Compliant with SFF-8636 management interface requirements
- Compliant with IEEE 802.3cd
- RoHS compliant

Applications

- 400G to 2×200G Ethernet Breakout Connectivity
- High-Performance Computing (HPC)
- AI/ML and GPU Computing Networks
- Data Center and Cloud Networking
- Switch-to-Server and Switch-to-NIC Interconnections
- High-Density Data Center Cabling

Description

The O400-2Q200-C is a high-performance passive direct attach copper (DAC) breakout cable designed for short-reach, high-bandwidth interconnections in data center and high-performance computing environments. It connects one 400G OSFP port to two independent 200G QSFP56 ports, enabling 400G-to-2×200G breakout connectivity. The cable utilizes eight 53.125 Gb/s PAM4 electrical lanes, with four lanes allocated to each 200G QSFP56 branch.

Featuring a passive shielded twinaxial copper architecture without active signal-conditioning components in the high-speed data path, the O400-2Q200-C provides low-latency connectivity and low power consumption. Available in 26 AWG, 28 AWG and 30 AWG options and lengths from 0.5 m to 3 m, it is suitable for short-distance interconnections between switches, servers, network adapters, and storage systems.

The hot-pluggable OSFP and QSFP56 interfaces simplify deployment, while the two-wire I²C management interface supports EEPROM-based cable identification and customizable vendor information. Its 1-to-2 breakout architecture enables a single 400G OSFP port to connect directly to two independent 200G QSFP56 ports, improving port utilization and simplifying high-density data center cabling.

The cable is designed in accordance with OSFP MSA, QSFP56 MSA, SFF-8679, SFF-8636, IEEE 802.3cd, and RoHS requirements.

Product performance Specifications

1、Absolute Maximum Ratings

Parameter	Symbol	Min	Typ.	Max	Unit
Storage Temperature	TS	-40		+85	°C

2、Recommended Operating Conditions

Parameter	Symbol	Min	Typ.	Max	Unit
Operating Case Temperature	TC	0		+70	°C
Power Supply Voltage	VCC	3.135	3.3	3.465	V
Relative Humidity	RH	5		85	%

3、General Product Specifications

Parameter	Specification	Condition
Product Type	Passive Direct Attach Copper (DAC) Breakout Cable	
Connector Configuration	1 × 400G OSFP to 2 × 200G QSFP56	1-to-2 breakout

Aggregate Data Rate	400 Gbps	2 × 200 Gbps
Raw Electrical Line Rate	425 Gbps	8 × 53.125 Gb/s
Electrical Signaling	PAM4	
Data Rate per Lane	53.125 Gb/s	
Symbol Rate per Lane	26.5625 GBd	PAM4
Electrical Lane Configuration	8 Tx + 8 Rx differential pairs at the OSFP end; 4 Tx + 4 Rx differential pairs per QSFP56 branch	
Cable Length	0.5–3 m	
Cable Gauge	26 AWG, 28 AWG, 30 AWG	
Cable Type	Passive Shielded Twinaxial Copper	
Hot Pluggable	Supported	
Management Interface	Two-wire I²C	
Module Identification	EEPROM	

4、Power Supply and Electrical Characteristics

Parameter	Symbol	Min	Typ.	Max	Unit
Power Dissipation per End	PD			0.1	W
Current per Signal Contact				0.5	A
Voltage per Contact				30	VDC
Low-Level Contact Resistance	LLCR			2	Ω
Insulation Resistance	Rins	10			MΩ

5、High-Speed Signal Integrity Characteristics

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Differential Impedance	Zdiff	90	100	110	Ω	TDR
Differential Insertion Loss	SDD21 / SDD12			17.16	dB	At 13.28 GHz
Differential Impedance	Zdiff	90	100	110	Ω	TDR
Differential Insertion Loss	SDD21 / SDD12			17.16	dB	At 13.28 GHz

6、Frequency-Dependent Signal Integrity Limits

Parameter	Symbol	Frequency Range (GHz)	Requirement	Unit
Differential Return Loss	SDD11 / SDD22	0.05 ≤ f < 4.1	≥ 16.5 − 2√f	dB
		4.1 ≤ f ≤ 10	≥ 10.66 − 14log10(f/5.5)	dB
Differential-to-Common-Mode Conversion Loss Difference	SCD21 − SDD21	0.01 ≤ f < 12.89	≥ 10	dB
		12.89 ≤ f < 15.7	≥ 27 − (29/22)f	dB
		15.7 ≤ f ≤ 19	≥ 6.3	dB

7、Cable Construction

Parameter	Specification
Cable Architecture	16 differential signal pairs (8 Tx + 8 Rx)
Cable Type	Shielded Twinaxial Copper
Conductor Material	Solid silver-plated copper
Conductor Gauge	26 AWG, 28 AWG, 30 AWG
Pair Drain Wire	28 AWG for 26 AWG cable; 30 AWG for 28 AWG and 30 AWG cable
Insulation Material	Foam polyolefin
Overall Cable Shield	Aluminum/polyester tape and tinned copper braid
Foil Coverage	125%
Braid Specification	38 AWG; 85% coverage
Jacket Material	PVC

8、Cable Electrical and Physical Characteristics by AWG

Parameter	26 AWG	28 AWG	30 AWG	Unit
Differential Impedance	100±5	100±5	100±5	Ω
Mutual Capacitance	14	14	14	pF/ft
Propagation Delay	1.35	1.35	1.35	ns/ft
Intra-Pair Skew	120 ps / 8.5 m maximum	120 ps / 7 m maximum	50 ps / 5.5 m maximum	
Inter-Pair Skew	500 ps / 8.5 m maximum	500 ps / 7 m maximum	350 ps / 5.5 m maximum	
Conductor DC Resistance at 20°C (Typical)	0.041	0.065	0.103	Ω/ft

Outer Cable Diameter	5.2	4.7	4.2	mm

9、Mechanical Performance

Parameter	Test Condition	Specification	Unit
OSFP Mating Force	10 mm/min	<40	N
QSFP56 Mating Force	10 mm/min	<60	N
OSFP Unmating Force	10 mm/min	<30	N
QSFP56 Unmating Force	10 mm/min	<30	N
Latch Retention Force	Latch engaged	≥125	N
Bulk Cable Retention in Module	Cable assembly only	≥90	N
Mechanical Durability	Plug/unplug cycles	≥50	Cycles
Minimum Bend Radius		10 × Cable OD	

OSFP Pin-out Definition



Figure4:Pin view(OSFP)

OSFP Pin Function Definitions

Pin	Logic	Symbol	Description	Note
1		GND	Ground	
2	CML-I	TX2p	Transmitter Data Non-Inverted	
3	CML-I	TX2n	Transmitter Data Inverted	
4		GND	Ground	
5	CML-I	TX4p	Transmitter Data Non-Inverted	
6	CML-I	TX4n	Transmitter Data Inverted	
7		GND	Ground	
8	CML-I	TX6p	Transmitter Data Non-Inverted	
9	CML-I	TX6n	Transmitter Data Inverted	
10		GND	Ground	
11	CML-I	TX8p	Transmitter Data Non-Inverted	
12	CML-I	TX8n	Transmitter Data Inverted	
13		GND	Ground	
14	LVCMOS-I/O	SCL	2-wire Serial interface clock	1
15		VCC	+3.3V Power	
16		VCC	+3.3V Power	
17	Multi-Level	LPWn/PRSn	Low-Power Mode / Module Present	2
18		GND	Ground	

19	CML-O	RX7n	Receiver Data Inverted	
20	CML-O	RX7p	Receiver Data Non-Inverted	
21		GND	Ground	
22	CML-O	RX5n	Receiver Data Inverted	
23	CML-O	RX5p	Receiver Data Non-Inverted	
24		GND	Ground	
25	CML-O	RX3n	Receiver Data Inverted	
26	CML-O	RX3p	Receiver Data Non-Inverted	
27		GND	Ground	
28	CML-O	RX1n	Receiver Data Inverted	
29	CML-O	RX1p	Receiver Data Non-Inverted	
30		GND	Ground	
31		GND	Ground	
32	CML-O	RX2p	Receiver Data Non-Inverted	
33	CML-O	RX2n	Receiver Data Inverted	
34		GND	Ground	
35	CML-O	RX4p	Receiver Data Non-Inverted	
36	CML-O	RX4n	Receiver Data Inverted	
37		GND	Ground	
38	CML-O	RX6p	Receiver Data Non-Inverted	
39	CML-O	RX6n	Receiver Data Inverted	
40		GND	Ground	
41	CML-O	RX8p	Receiver Data Non-Inverted	
42	CML-O	RX8n	Receiver Data Inverted	
43		GND	Ground	
44	Multi-Level	INT/RSTn	Module Interrupt / Module Reset	2
45		VCC	+3.3V Power	
46		VCC	+3.3V Power	
47	LVCMOS-I/O	SDA	2-wire Serial interface data	1
48		GND	Ground	
49	CML-I	TX7n	Transmitter Data Inverted	
50	CML-I	TX7p	Transmitter Data Non-Inverted	
51		GND	Ground	
52	CML-I	TX5n	Transmitter Data Inverted	
53	CML-I	TX5p	Transmitter Data Non-Inverted	
54		GND	Ground	
55	CML-I	TX3n	Transmitter Data Inverted	
56	CML-I	TX3p	Transmitter Data Non-Inverted	
57		GND	Ground	
58	CML-I	TX1n	Transmitter Data Inverted	

59	CML-I	TX1p	Transmitter Data Non-Inverted	
60		GND	Ground	

Note1: Open-Drain with pull up resistor on Host.

Note2: See pin description for required circuit.

Pin-out Definition

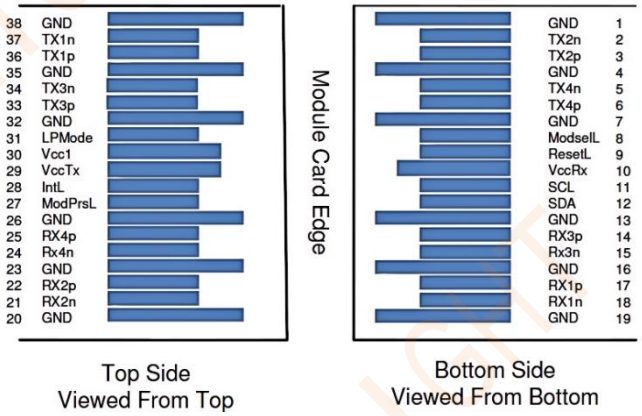


Figure4: Pin view

Pin Function Definitions

Pin	Logic	Symbol	Description	Note
1		GND	Ground	1
2	CML-I	Tx2n	Transmitter Inverted Data Input	3
3	CML-I	Tx2p	Transmitter Non-Inverted Data Input	3
4		GND	Ground	1
5	CML-I	Tx4n	Transmitter Inverted Data Input	3
6	CML-I	Tx4p	Transmitter Non-Inverted Data Input	3
7		GND	Ground	1
8	LVTTL-I	ModSelL	Module Select	4
9	LVTTL-I	ReSelL	Module Select	4
10		Vcc Rx	+3.3V Power Supply Receiver	2
11	LVCMOS-I/O	SCL	2-wire serial interface clock	4
12	LVCMOS-I/O	SDA	2-wire serial interface data	4
13		GND	Ground	1
14	CML-O	Rx3p	Receiver Non-Inverted Data Output	3

15	CML-O	Rx3n	Receiver Inverted Data Output	3
16		GND	Ground	1
17	CML-O	Rx1p	Receiver Non-Inverted Data Output	3
18	CML-O	Rx1n	Receiver Inverted Data Output	3
19		GND	Ground	1
20		GND	Ground	1
21	CML-O	Rx2n	Receiver Inverted Data Output	3
22	CML-O	Rx2p	Receiver Non-Inverted Data Output	3
23		GND	Ground	1
24	CML-O	Rx4n	Receiver Inverted Data Output	3
25	CML-O	Rx4p	Receiver Non-Inverted Data Output Ground	3
26		GND	Ground	1
27	LVTTL-O	ModPrsL	Module Present	4
28	LVTTL-O	IntL	Interrupt	4
29		Vcc Tx	+3.3V Power supply transmitter	2
30		Vcc1	+3.3V Power supply	2
31	LVTTL-I	LPMode	Low Power Mode	4
32		GND	Ground	1
33	CML-I	Tx3p	Transmitter Non-Inverted Data Input	3
34	CML-I	Tx3n	Transmitter Inverted Data Input	3
35		GND	Ground	1
36	CML-I	Tx1p	Transmitter Non-Inverted Data Input	3
37	CML-I	Tx1n	Transmitter Inverted Data Input	3
38		GND	Ground	1

Note1:GND is the symbol for signal and supply (power) common for the QSFP+ module. All are common within the QSFP+ module and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal-common ground plane.

Note2: Vcc Rx, Vcc1 and Vcc Tx are the receiver and transmitter power supplies and shall be applied concurrently. Requirements defined for the host side of the Host Edge Card Connector are listed in Table. Recommended host board power supply filtering is shown in Host board power supply circuit. Vcc Rx Vcc1 and Vcc Tx may be internally connected within the QSFP module in any combination. The connector pins are each rated for a maximum current of 500 mA.

Note3: High-speed signal interfaces require differential pairs (e.g. TX1+/TX1-) with tightly matched impedances (typically 100Ω).

Note4: The management and control signals are based on LVTTL level logic and are used for functions such as module selection and reset.

Monitoring Specification(OSFP)

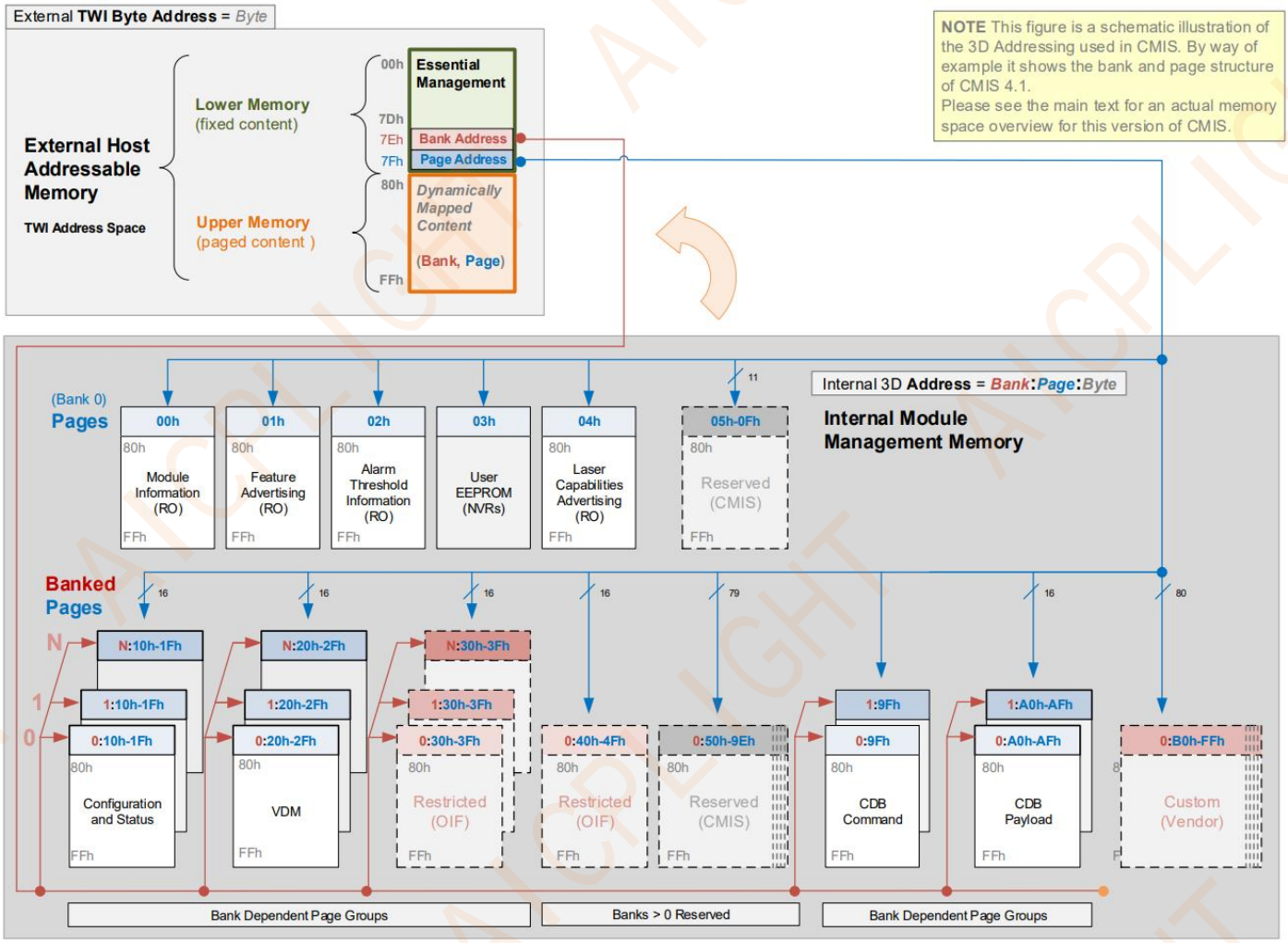


Figure5: Memory map

Memory map Table(OSFP)

Byte	Unit	Name	Description
Lower Page 00h			
0-2	3	Management Characteristics	Basic Information about how this module is managed
3	1	Global Status Information	Current state of Module, Interrupt signal status
4-7	4	Flag Summary	Summary of Flags set on specific Pages (and Banks)
8-13	6	Module-Level Flags	Flags that are not lane or Data Path specific
14-25	12	Module-Level Monitors	Monitors that are not lane or Data Path specific
26-30	5	Module-Level Controls	Controls applicable to the module as a whole
31-36	6	Module-Level Masks	Mask bits for the Module-Level Flags
37-38	2	CDB Command Status	Status of current CDB command
39-40	2	Module Active Firmware Version	Module Active Firmware Version number
41	1	Fault Information	Fault cause for entering ModuleFault state
42-63	22		Reserved
64-84	21		Custom
85-117	33	Supported Applications Advertising	Applications supported by module Data Path(s)
118-125	8	Password Facilities	Password Entry and Change (mechanism only)
126-127	2	Page Mapping	Page mapping into host addressable Upper Memory
Upper Page 00h			
128	1	SFF8024IdentifierCopy	Copy of Byte 00h:0
129-144	16	VendorName	Vendor name (ASCII)
145-147	3	Vendor OUI	Vendor IEEE company ID
148-163	16	Vendor PN	Part number provided by vendor (ASCII)
164-165	2	Vendor Rev	Revision level for part number provided by vendor (ASCII)
166-181	16	Vendor SN	Vendor Serial Number (ASCII)
182-189	8	DateCode	Manufacturing Date Code (ASCII)
190-199	10	CLEICode	Common Language Equipment Identification Code (ASCII)
200-201	2	ModulePowerCharacteristics	Module power characteristics
202	1	CableAssemblyLinkLength	Cable length (for cable assembly modules only)
203	1	ConnectorType	Connector type of the media interface
204-209	6	Copper Cable Attenuation	Attenuation characteristics (passive copper cables only)
210	1	MediaLaneInformation	Supported near end media lanes (all modules)
211	1	Cable Assembly Information	Far end modules information (cable assemblies only)
212	1	MediaInterfaceTechnology	Information on media side device or cable technology
213-220	8		Reserved
221	1		Custom
222	1	PageChecksum	Page Checksum over bytes 128-221
223-255	33		Custom

Monitoring Specification(QSFP56)

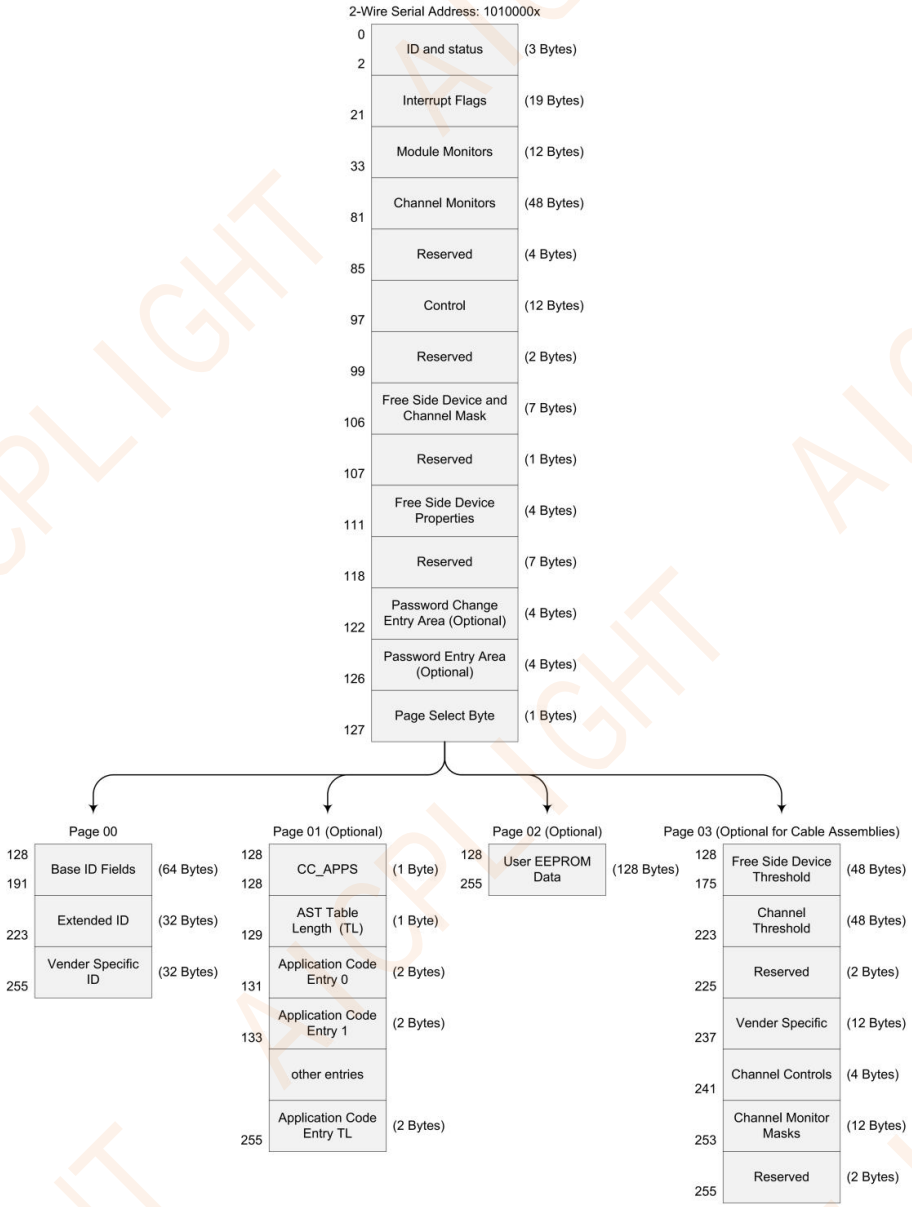


Figure5: Memory map

Memory map Table(QSFP56)

Byte	Unit	Name	Description
			Lower Page 00h
0	1	Identifier	Type of transceiver,Page 00h Byte 0 and Page 00h Byte 128 shall contain the same parameter values.
1	1	Status	Revision Compliance
2	1	Status	Status indicators

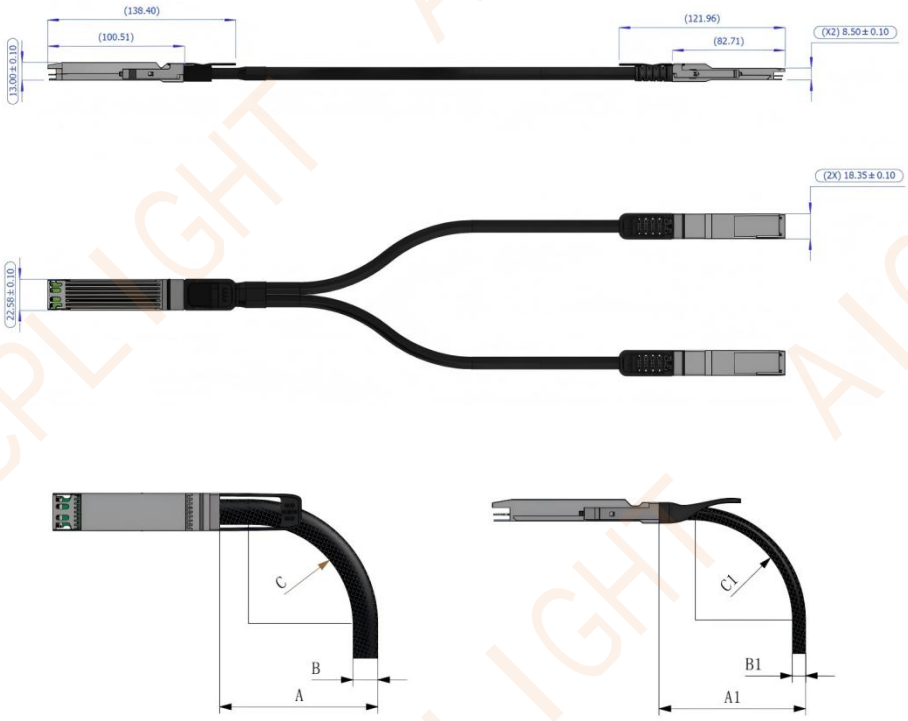
3-21	19	Interrupt Flags	Consist of interrupt flags for LOS, Tx Fault, warnings and alarms. The non-asserted state shall be 0b.
22	1	Temperature MSB	Internally measured temperature (MSB)
23	1	Temperature LSB	Internally measured temperature (LSB)
24-25	2	Reserved	Reserved
26	1	Supply Voltage MSB	Internally measured supply voltage (MSB)
27	1	Supply Voltage LSB	Internally measured supply voltage (LSB)
28-29	2	Reserved	Reserved
30-33	4	Vendor Specific	Vendor Specific
34	1	Rx1 Power MSB	Internally measured Rx1 input power
35	1	Rx1 Power LSB	
36	1	Rx2 Power MSB	Internally measured Rx2 input power
37	1	Rx2 Power LSB	
38	1	Rx3 Power MSB	Internally measured Rx3 input power
39	1	Rx3 Power LSB	
40	1	Rx4 Power MSB	Internally measured Rx4 input power
41	1	Rx4 Power LSB	
42	1	Tx1 Bias MSB	Internally measured Tx1 bias
43	1	Tx1 Bias LSB	
44	1	Tx2 Bias MSB	Internally measured Tx2 bias
45	1	Tx2 Bias LSB	
46	1	Tx3 Bias MSB	Internally measured Tx3 bias
47	1	Tx3 Bias LSB	
48	1	Tx4 Bias MSB	Internally measured Tx4 bias
49	1	Tx4 Bias LSB	
50	1	Tx1 Power MSB	Internally measured Tx1 Power
51	1	Tx1 Power LSB	
52	1	Tx2 Power MSB	Internally measured Tx2 Power
53	1	Tx2 Power LSB	
54	1	Tx3 Power MSB	Internally measured Tx3 Power
55	1	Tx3 Power LSB	
56	1	Tx4 Power MSB	Internally measured Tx4 Power
57	1	Tx4 Power LSB	
58-65	8	Reserved	Reserved channel monitor set 4
66-73	8	Reserved	Reserved channel monitor set 5
74-81	8	Vendor Specific	Vendor Specific
82-85	4	Reserved	Reserved
86-99	14	Control	Control
100-106	7	Free Side Device and Channel Masks	Free Side Device and Channel Masks
107-110	4	Free Side Device Properties	Free Side Device Properties

111-112	2	Assigned for use by PCI Express	Used for: - The PCI Express External Cable Specification - The PCI Express OCuLink Specification
113-117	4	Free Side Device Properties	Free Side Device Properties
118	1	Reserved	Reserved
119-122	4	Password Change Entry Area	Password Change Entry Area
123-126	4	Password Entry Area	Password Entry Area
127	1	Page Select Byte	Page Select Byte
Upper Page 00h			
128	1	Identifier	Identifier Type of free side device.(See SFF-8024 Transceiver Management)
129	1	Ext. Identifier	Extended Identifier of free side device. Includes power classes, CLEI codes, CDR capability.
130	1	Connector Type	Code for media connector type. (See SFF-8024 Transceiver Management)
131-138	8	Specification Compliance	Code for electronic or optical compatibility.
139	1	Encoding	Code for serial encoding algorithm. (See SFF-8024 Transceiver Management)
140	1	Signaling rate, nominal	Nominal signaling rate, units of 100 MBd. For rate > 25.4 GBd, set this to FFh and use Byte 222.
141	1	Extended Rate Select Compliance	Tags for extended rate select compliance.
142	1	Length (SMF)	Link length supported at the signaling rate in byte 140 or page 00h byte 222, for SMF fiber in km *. A value of 1 shall be used for reaches from 0 to 1 km.
143	1	Length (OM3 50 um)	Link length supported at the signaling rate in byte 140 or page 00h byte 222, for EBW 50/125 um fiber (OM3), units of 2 m *
144	1	Length (OM2 50 um)	Link length supported at the signaling rate in byte 140 or page 00h byte 222, for 50/125 um fiber (OM2), units of 1 m *
145	1	Length (OM1 62.5 um) or Copper Cable Attenuation	Link length supported at the signaling rate in byte 140 or page 00h byte 222, for 62.5/125 um fiber (OM1), units of 1 m *, or copper cable attenuation in dB at 25.78 GHz.
146	1	Length (passive copper or active cable or OM4 50 um)	Length of passive or active cable assembly (units of 1 m) or link length supported at the signaling rate in byte 140 or page 00h byte 222, for OM4 50/125 um fiber (units of 2 m) as indicated by Byte 147. See 6.3.12.
147	1	Device technology	Device technology
148-163	16	Vendor name	Free side device vendor name (ASCII)
164	1	Extended Module	Extended Module codes for InfiniBand.
165-167	3	Vendor OUI	Free side device vendor IEEE company ID.
168-183	16	Vendor PN	Part number provided by free side device vendor(ASCII)
184-185	2	Vendor rev	Revision level for part number provided by the vendor(ASCII)

186-187	2	Wavelength or Copper Cable Attenuation	Nominal laser wavelength (wavelength=value/20 in nm) or copper cable attenuation in dB at 2.5 GHz (Byte 186) and 5.0 GHz (Byte 187)
188-189	2	Wavelength tolerance or Copper Cable Attenuation	The range of laser wavelength (+/- value) from nominal wavelength. (wavelength Tol. =value/200 in nm) or copper cable attenuation in dB at 7.0 GHz (Byte 188) and 12.9 GHz (Byte 189)
190	1	Max case temp	Maximum case temperature
191	1	CC_BASE	Check code for base ID fields (Bytes 128-190)
192	1	Link codes	Extended Specification Compliance Codes (See SFF-8024)
193-195	3	Options	Optional features implemented.
196-211	16	Vendor SN	Serial number provided by vendor.(ASCII)
212-219	8	Date Code	Vendor's manufacturing date code.
220	1	Diagnostic Monitoring Type	Indicates which type of diagnostic monitoring is implemented (if any) in the free side device. Bit 1,0 Reserved.
221	1	Enhanced Options	Indicates which optional enhanced features are implemented in the free side device.
222	1	CC_EXT	Check code for the Extended ID Fields (Bytes 192-222)
224-255	32	Vendor Specific	Vendor Specific EEPROM
Page 02h (Optional)			
128-255	128	User EEPROM Data	
Page 03h (Optional)			
128-129	2	Temp High Alarm	MSB at lower byte address
130-131	2	Temp Low Alarm	MSB at lower byte address
132-133	2	Temp High Warning	MSB at lower byte address
134-135	2	Temp Low Warning	MSB at lower byte address
136-143	8	Reserved	Reserved
144-145	2	Vcc High Alarm	MSB at lower byte address
146-147	2	Vcc Low Alarm	MSB at lower byte address
148-149	2	Vcc High Warning	MSB at lower byte address
150-151	2	Vcc Low Warning	MSB at lower byte address
152-159	8	Reserved	Reserved
160-175	16	Vendor Specific	Vendor Specific
176-177	2	Rx Power High Alarm	MSB at lower byte address
178-179	2	Rx Power Low Alarm	MSB at lower byte address
180-181	2	Rx Power High Warning	MSB at lower byte address
182-183	2	Rx Power Low Warning	MSB at lower byte address
184-185	2	Tx Bias High Alarm	MSB at lower byte address
186-187	2	Tx Bias Low Alarm	MSB at lower byte address
188-189	2	Tx Bias High Warning	MSB at lower byte address
190-191	2	Tx Bias Low Warning	MSB at lower byte address
192-193	2	Tx Power High Alarm	MSB at lower byte address
194-195	2	Tx Power Low Alarm	MSB at lower byte address
196-197	2	Tx Power High Warning	MSB at lower byte address

198-199	2	Tx Power Low Warning	MSB at lower byte address
200-207	8	Reserved	Reserved thresholds for channel parameter set 4
208-215	8	Reserved	Reserved thresholds for channel parameter set 5
216-223	8	Vendor Specific	Vendor Specific
224	1	Tx EQ & Rx Emphasis Magnitude ID	Tx EQ & Rx Emphasis Magnitude ID
225	1	Rx output amplitude support indicators	Rx output amplitude support indicators
226-229	4	Control options advertising	Control options advertising
230-241	12	Optional Channel Controls	Optional Channel Controls
242-247	6	Channel Monitor Masks	Channel Monitor Masks
248-249	2	Reserved	Reserved channel monitor masks set 4
250-251	2	Reserved	Reserved channel monitor masks set 5
252-255	4	Reserved	Reserved

Mechanical Dimension



Note:

- All dimensions are in mm.
- Unless otherwise specified, dimensional tolerance is ±0.1 mm.
- Latch color: Black.
- Cable length tolerance: ±25 mm for L < 2 m and ±50 mm for L ≥ 2 m.

Handling and Safety Precautions:

- ESD Precautions: Follow standard ESD handling procedures when handling or installing the cable assembly, particularly at the connector ends.
- Bend Radius: Do not bend the cable below the specified minimum bend radius. Avoid sharp bends or repeated bending near the connector strain-relief area.
- Cable Handling: Avoid excessive pulling, twisting, crushing, kinking, or other mechanical stress that may damage the cable or affect signal integrity.
- Installation and Removal: Use the pull tab or release mechanism when inserting or removing the cable assembly. Do not pull directly on the cable.
- Connector Protection: Keep the electrical connector contacts clean and protected from dust, moisture, and contamination when not installed.
- Cable Assembly Protection: Do not disassemble, modify, splice, or attempt to repair the cable assembly or connector housing. Replace the cable if physical damage is observed.

Ordering Information

PN	Description
O400-2Q200-C1	400G OSFP Finned Top to 2× 200G QSFP56 Passive Direct Attach Copper Breakout Cable,1m
O400-2Q200-C1.5	400G OSFP Finned Top to 2× 200G QSFP56 Passive Direct Attach Copper Breakout Cable,1.5m
O400-2Q200-C2	400G OSFP Finned Top to 2× 200G QSFP56 Passive Direct Attach Copper Breakout Cable,2m
O400-2Q200-C3	400G OSFP Finned Top to 2× 200G QSFP56 Passive Direct Attach Copper Breakout Cable,3m